To the Honorable Director of the United States Patent and Trademark Office. Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
   KOO, Kyeong-mo
   KU, Ja-hum
   PARK, Hye-jeong

   Additional names(s) of conveying party(ies)  Yes  No

2. Name and address of receiving party(ies):
   Name: SAMSUNG ELECTRONICS CO., LTD.
   Address: 416, Maetan-dong, Yeongtong-gu.

   City: Suwon-si, Gyeonggi-do
   State/Prov.: 
   Country: Republic of Korea
   ZIP: 

   Additional name(s) & address(es)  Yes  No

3. Nature of conveyance:
   Assignment  Yes  No
   Merger  No
   Security Agreement  No
   Change of Name  No
   Other  No

   Execution Date: FEBRUARY 13, 17, 16, 2004

4. Application number(s) or patent numbers(s):
   If this document is being filed together with a new application, the execution date of the application is:

   Patent Application No. 10/686,768
   Filing date 10/17/2003

   Additional numbers  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: ADAM C. VOLENTINE
   Registration No. 33289
   Address: VOLONENT FRANCOS, PLLC
   12200 SUNRISE VALLEY DRIVE, SUITE 150
   City: RESTON
   State/Prov.: VA
   Country: U.S.A.
   ZIP: 20191

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): $ 40.00
   Enclosed - Any excess or insufficiency should be credited or debited to deposit account
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8. Deposit account number:
   50-0238
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   To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

ADAM C. VOLENTINE
Name of Person Signing

MARCH 12, 2004
Date

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PATENT
REEL: 015077 FRAME: 0771
ASSIGNMENT

In consideration of the sum of One Dollar ($1.00) and other good and valuable consideration paid to each of the undersigned

Insert
Name(s) of
Inventor(s)

Kyeong-nan Koo

Ja-hun KI

Hyung-jong PARK

the undersigned hereby sell(s) and assign(s) to

Insert
Name(s) of
Assignee(s) &

Samsung Electronics Co., Ltd.

Address(es)

of 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea

Title of
Invention

(hereinafter designated as the Assignee) the entire right, title and interest for the United States as defined in 35 USC 100, in the invention known as

Method of Forming Cobalt Silicide Film and Method of Manufacturing Semiconductor Device Having Cobalt Silicide Film

Date of
Signing of
Application

for which an application for patent in the United States of America has been executed by

the undersigned on

The undersigned agree(s) to execute all papers necessary in connection with this application and any continuing, divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuing, division or reissue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing or reissue applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed, and will not execute, any agreement in conflict herewith.

Page 1 of 2
<table>
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<tr>
<td>Kyeong-mo Koo</td>
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I further declare that all statements made herein of my own knowledge are true, and that all statements on information and believe are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Applicant Reference No. SS-20288-US  Atty Docket No. SEC.1034CIP

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